

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph [0054] beginning on page 23, line 31 and ending on page 24, line 15, with the following amended paragraph:

The sealing structures of the heat sink portions, etc., shall now be explained using Fig. 19 to Fig. 21. Fig. 19 is the sectional view of the sealing structure between the heat sink 10, to which the leg 13 has been mounted, and the main casing body 2, Fig. 20 is the perspective view for depicting the positioning of the caulking with respect to the heat sink 10 to which the leg 13 has been mounted, and Fig. 21 is the three-view drawing for depicting the positioning of the caulking with respect to the heat sink 10, to which the leg 13 has been mounted, and the main casing body 2. As shown in these drawings, the caulking 80 is applied to the entire periphery of the heat sink 10 to eliminate gaps between the heat sink 10 and the main casing body 2 and prevent the entry of rainwater into inner portions of the main casing body 2. Also as shown in Fig. 21, a caulking 81 is applied to the inner side of the upper protrusions 2e of the left and right side plates 2d of the main casing body 2.

Please replace the paragraph [0056] beginning on page 24, line 30 and ending on page 25, line 10, with the following amended paragraph:

As shown in Fig. 22, the power circuit boards 30 are mounted on the back surface of the base plate 12 of the heat sink 10. Also, power substrates elements 91

of high-voltage drive that are large in heat generating amount, such as an IGBT (Insulated Gate Bipolar Transistor) that is electrically connected to the power circuit boards 30 are mounted on flat, small heat sink 90. Because entry of rainwater to such power elements 91 of high-voltage drive must be avoided as much as possible, a keel 92 is formed on an upper portion of the small heat sink 90, and as the keel 92, one that is not horizontal but is inclined to the left or right is employed. Fig. 23 is the plan view of the small heat sink with the keel 92 and here, the keel 92 is inclined at an angle ϕ .

Please replace the paragraph [0057] beginning on page 25, line 11 and ending on page 25, line 19, with the following amended paragraph:

With the small heat sink 90 having the keel 92, the rainwater that enters into the area in which the electronic circuit boards are mounted and flow down along the back face of the base plate 12 of the heat sink 10 is stopped by the keel 92 and thereafter flows downward along the inclination of the keel 92. The entry of rainwater to the power circuit boards elements 91 that are electronic circuits mounted on the heat sink 90 can thus be prevented definitely.